



Applied Materials Mirra
Integra
Poly/STI CMP
Serial Number L-402

**Currently Configured for 200mm wafer
size MFG Date: 1999**

EQUIPMENT DETAILS:

- **Wafer Size (inches) : 8**
- **Install Type : Through-the-wall**
- **Date of Manufacture: 06/28/99**
- **Software Version : MB60a1**
- **CPU Board Type :**
Pentium 3 400MHz or
Higher : Yes
- **Electrical Requirements : 200/208VAC**
- **Process Type: Polysilicon**
- **Mainframe: Mirra**

**Track o Dry In/Dry
Out**

- o **Signal Lamp Tower**
- o **Integrated SMIF (qty 3 loaders)**
- o **Cassette Tank : Standard**
- o **Robot Type : 112"**
- o **Cleaner Type : Ontrak**
- o **Cleaner Chemicals Used : NH4OH**
- o **E-Chain Lifetime : Since installation**
- o **Cleaning Package : No**
- o **Spray Gun : Single**
- o **In-Situ Removal Rate Monitor : Motor
Torque**
- o **Metrology Option : None**
- o **IPM : No**
- **Mirra Polish**

- **Heads**
 - o **Titan 1 Polish Heads**
 - o **PPS Retaining Rings**
 - o **Standard Wafer Loss Sensor**
- **Mirra Platens**
 - o **Teflon Coated Platens : No**
 - o **Pad Type : IC 1000**
 - o **Pad Conditioner Head : P4**
- Intel**
 - o **Pad Conditioner Disc : EWHA**
 - o **Universal Disk Holder : No**
 - o **Temperature Control : None**
- **Slurries**
 - o **Slurries/Platen Used : 1**
 - o **Chemicals Used : Oxide Slurry**
 - o **Flow Rate : Standard**
 - o **Dispense Arm : Standard**
 - o **Slurry Flow Monitors : Yes**





